Docket No. ONDAT-015CUS

This listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims:

1. (Currently amended) A hot plate unit useable for heating a wafer comprising:

a casing having a bottom and a first opened portion;

a ceramic nitride or ceramic carbide hot plate arranged in the first opened portion and having an upper surface opposed to the wafer and a bottom surface opposed to the bottom of the casing and on which a heating element is attached, wherein the hot plate and the casing define a space in which a cooling fluid flows; and

an intake port attached to the bottom of the casing for enabling the intake of the cooling fluid inside the casing, wherein the intake port faces the bottom surface of the hot plate, and wherein a plurality of second openings are formed in the bottom of the casing.

2. (Cancelled) The hot plate unit according to claim 1, further comprising an intake port attached to the casing for enabling the intake of a fluid.

3. (Currently amended) The hot plate unit according to claim [[2]] 1, wherein the intake port includes a plurality of intake ports.

4. (Cancelled) The hot plate unit according to any one of claims 1 to 3, wherein the second opening includes a plurality of second openings.

5. (Currently amended) The hot plate unit according to ~~any one of claims 2 or~~ claim 3, wherein the ~~cooling~~ fluid includes air.

6. (Currently amended) A hot plate unit comprising:

a ceramic nitride or ceramic carbide hot plate having a first surface, for heating a wafer;

a heating element attached on a second surface of the hot plate; and

a casing for supporting the hot plate and for covering the heating element, wherein the casing includes a bottom facing the second surface of the hot plate, a first opened portion covered by the hot plate, an intake port attached to the bottom of the casing for enabling the intake of a cooling fluid inside the casing, and a plurality of second openings formed in the bottom of the casing for discharging the cooling fluid from the casing and for lowering heat capacity of the bottom of the casing.

7. (New) The hot plate unit according to claim 1, wherein the heating element is formed on the bottom surface of the hot plate.

8. (New) The hot plate unit according to claim 6, wherein the intake port faces the heating element.

9. (New) A hot plate unit for heating a semiconductor wafer, consisting of:

a ceramic nitride or ceramic carbide hot plate having an upper surface facing the wafer and a bottom surface;

a heating element attached on the bottom surface of the hot plate and having external connection terminals;

a casing for supporting the hot plate and for covering the heating element, wherein the casing and the bottom surface of the hot plate form an internal space in which a cooling fluid flows, and the casing has a bottom including a plurality of holes for directly discharging the cooling fluid from the internal space and for lowering heat capacity of the bottom of the casing.